



HV-MAPS for the Mighty-Tracker of the upgraded LHCb detector

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LHCb – a forward spectrometer at the LHC

- Designed to explore large cross section for $b\bar{b}$, $c\bar{c}$ production in the forward region

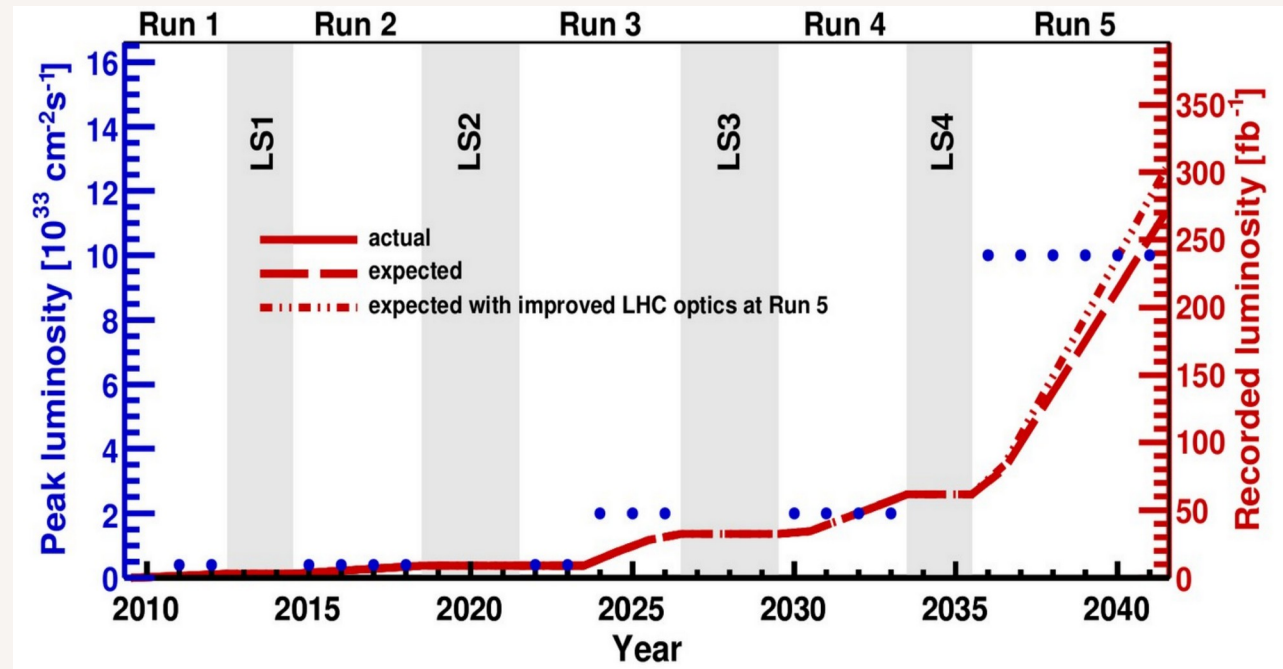
- Integrated luminosity:

today: 31.7 fb^{-1}

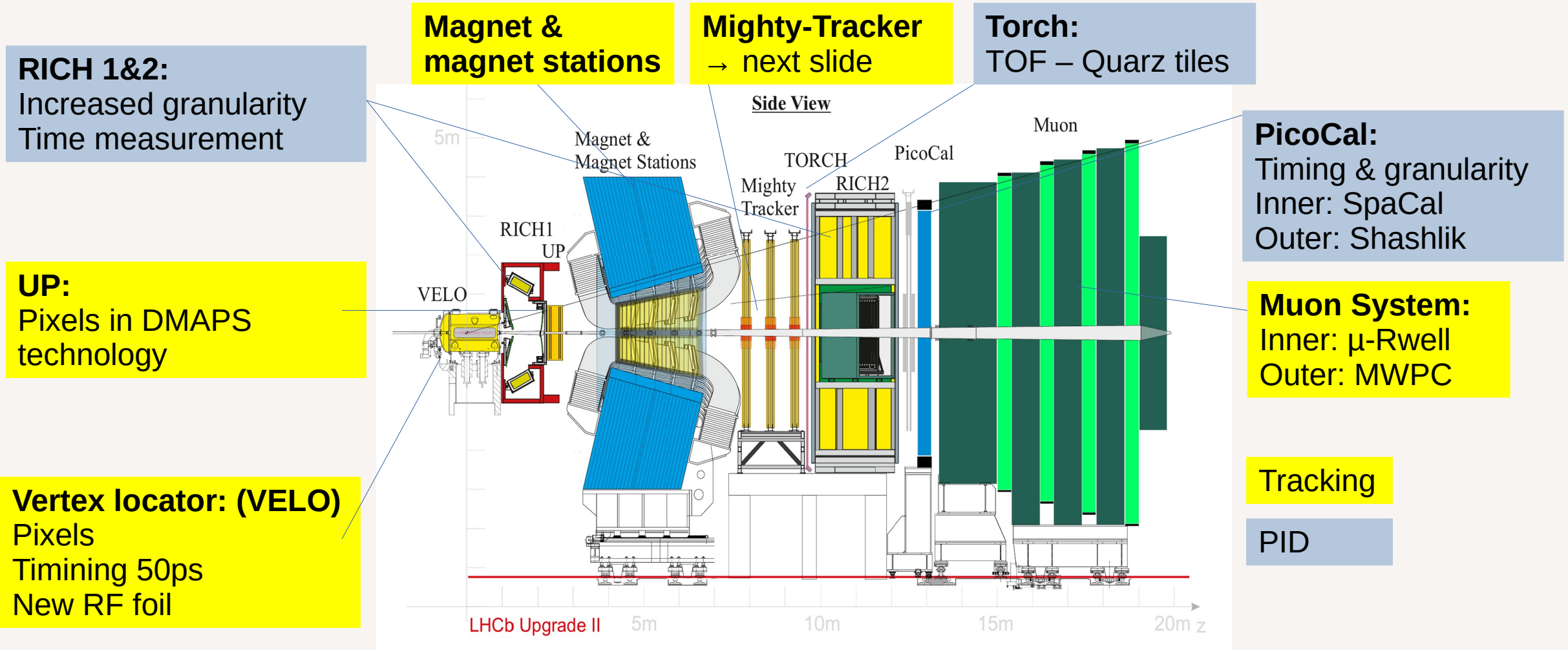
end of Run 4: $\sim 50 \text{ fb}^{-1}$

end of Run 5: $\sim 300 \text{ fb}^{-1}$

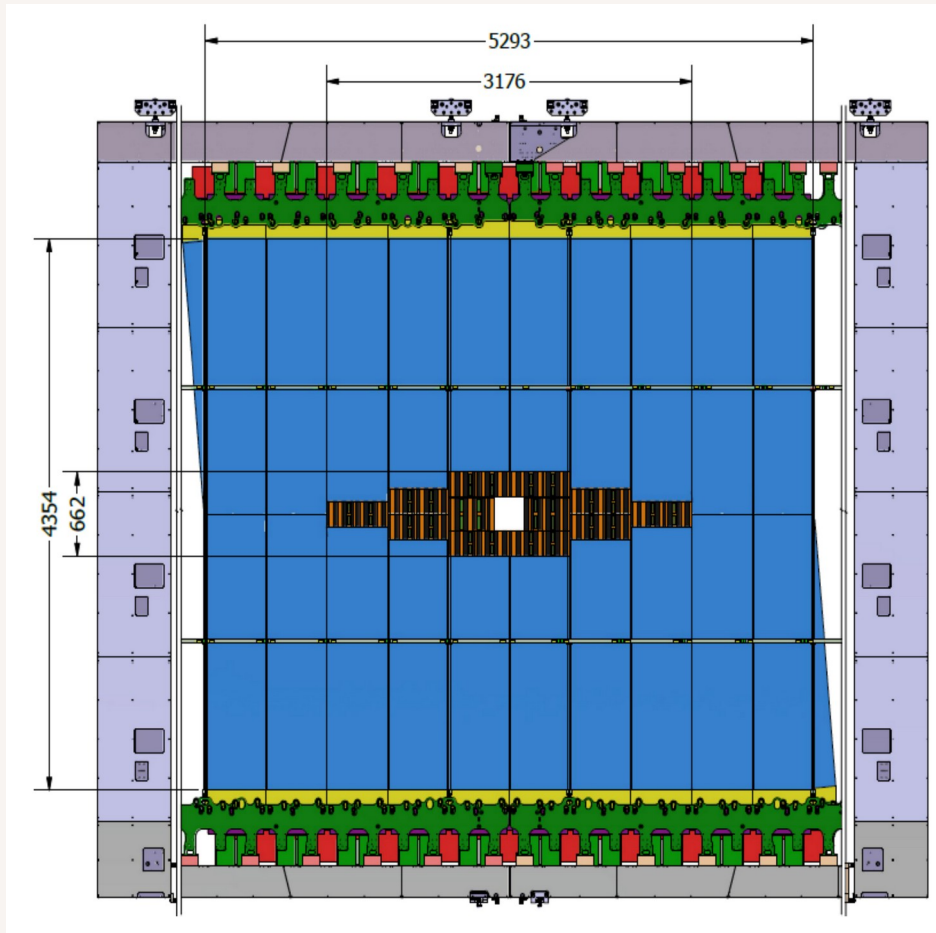
- Very broad physics program:
flavor physics, rare decay & CP-violation, EW physics, QCD, exotic particles, fixed target, heavy ion physics



The LHCb Upgrade II



The Mighty-Tracker



Outer region (Mighty-SciFi):

- 3 stations à 4 layers → $\sim 300\text{m}^2$ detector area
- scintillating fibres with SiPM readout
- $250\mu\text{m}$ fibres
- SiPM operated at liquid N_2 temperatures

Inner region (Mighty-Pixel):

- Silicon pixels in HV-MAPS technology
- 6 layers à 1.3m^2
- Options for Mighty-Pixel sensor:

MightyPix ← this talk

RadPix ← DRD3 development

Challenges for the MightyPixel:

Environment:

- Particle rate: 13MHz/cm^2 *
- NIEL: $2.5 \times 10^{14} \text{ n}_{\text{eq}}/\text{cm}^2$ *
- TID: 40 MRad *
- Bunch crossing spacing: 25 ns

Material budget:

- Per layer: $1\text{-}2\% \text{ X0}$

* numbers do not include
safety factors

Powering & power consumption:

- Power consumption $<150\text{mW/cm}^2$
- Serial powering

Slow control:

- Large system : $\sim 22\text{k}$ sensors
 $\text{O}(10^9)$ channels

SPECIFICATIONS IN A NUTSHELL

- The sensors have to guarantee an in-time efficiency* of $>99\%$ over the entire lifetime of the experiment at a power consumption $< 150\text{mW/cm}^2$.
- Spatial resolution is given by the binary resolution of pixels

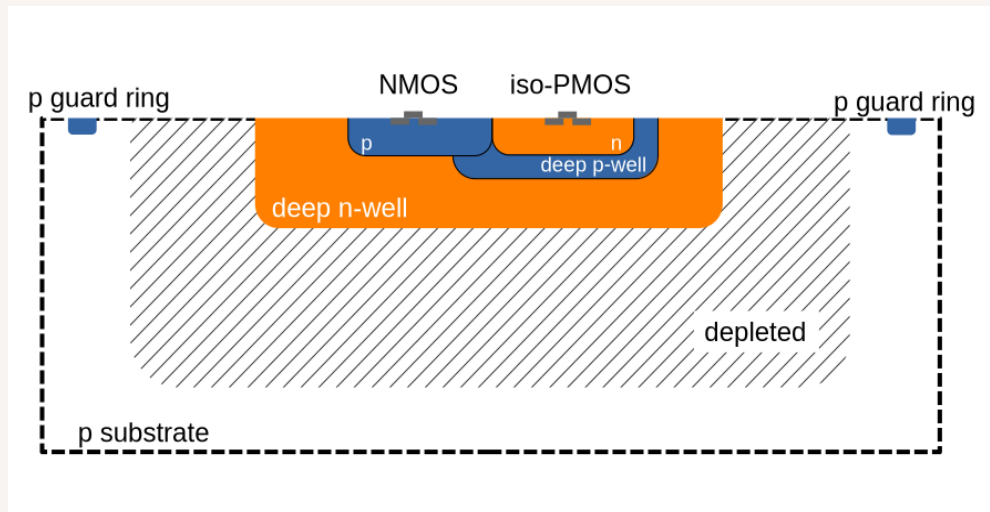
(*i.e. an hit efficiency $> 99\%$ with correct bunch crossing identification, corresponding to $\sim 3\text{ns}$ time resolution for a 25ns bunch crossing spacing)

HV-MAPS technology

I. Peric, Nucl.Instrum.Meth. A582 (2007) 876-885

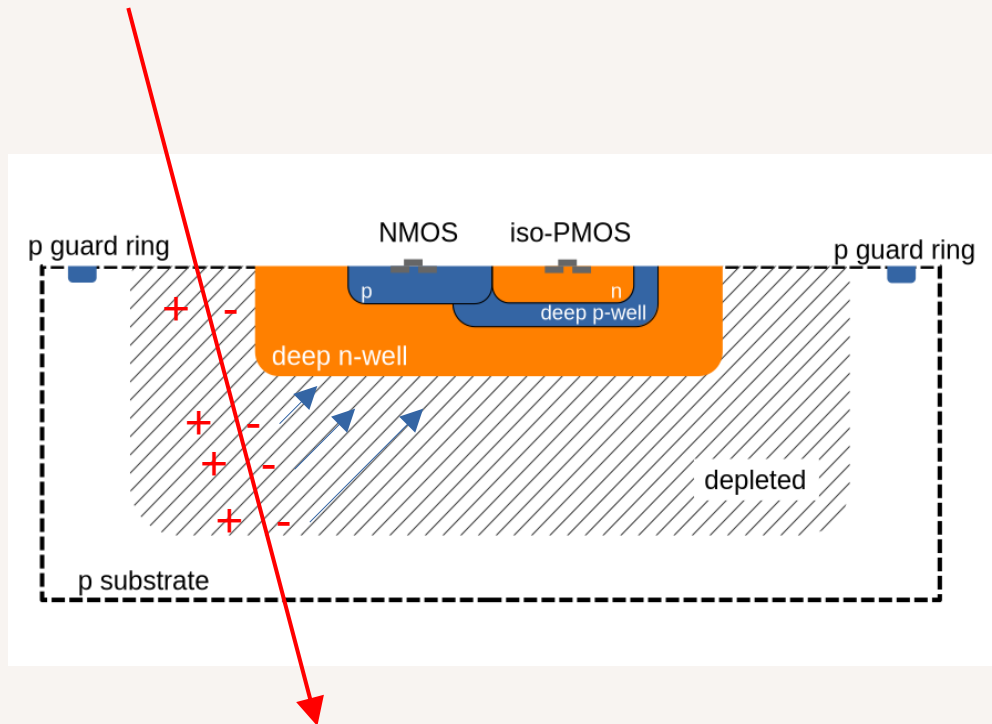
- **produced in commercial HV-CMOS processes**

- **pn junction formed by reverse biased deep n-well and p substrate**

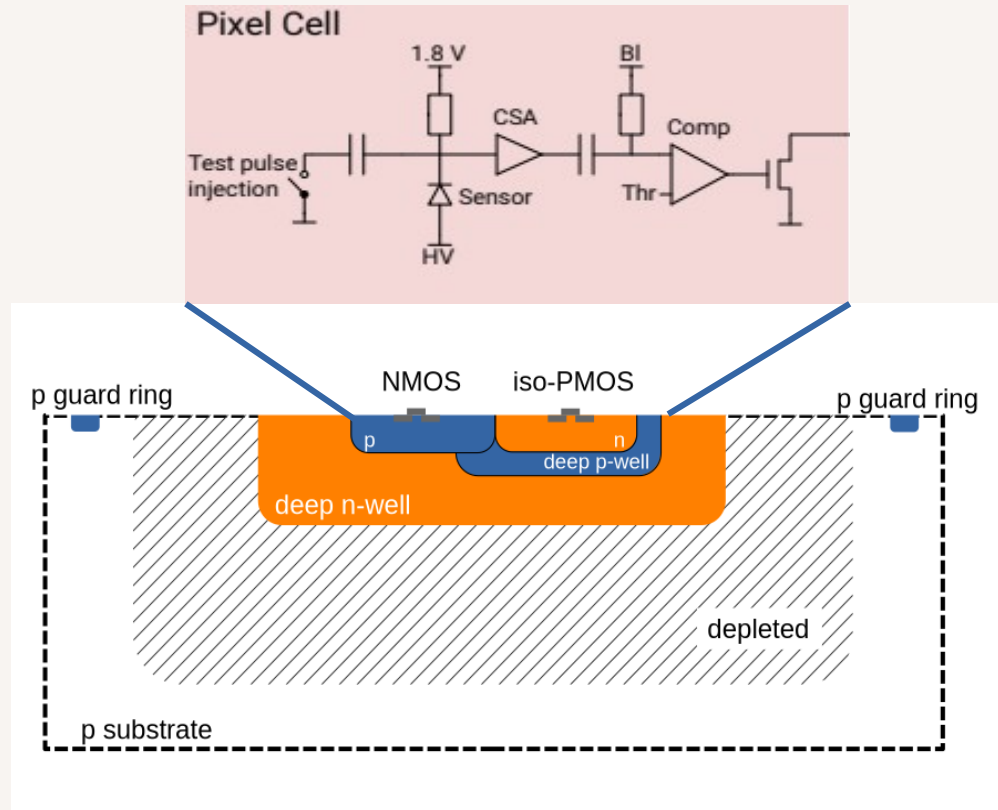


HV-MAPS technology

- produced in commercial HV-CMOS processes
- pn junction formed by reverse biased deep n-well and p substrate
- **fast charge collection via drift**

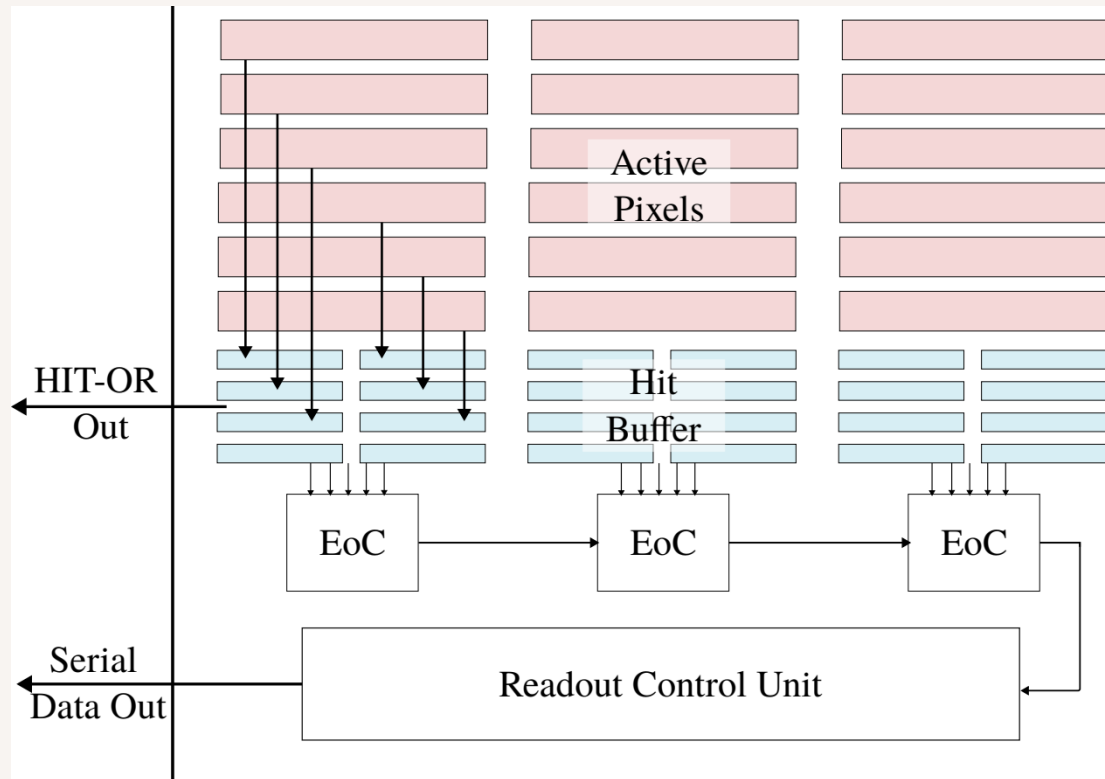


HV-MAPS technology



- produced in commercial HV-CMOS processes
- pn junction formed by reverse biased deep n-well and p substrate
- fast charge collection via drift
- **every pixel houses tuneable amplifier & comparator**

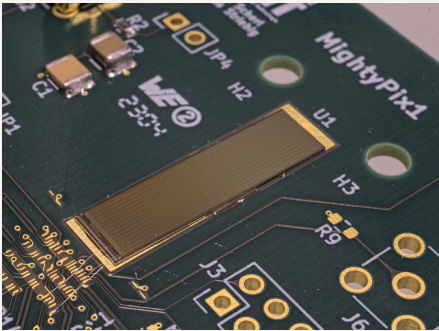
HV-MAPS technology



- produced in commercial HV-CMOS processes
- pn junction formed by reverse biased deep n-well and p substrate
- fast charge collection via drift
- every pixel houses tuneable amplifier & comparator
- **hit information (ToA, ToT) stored in periphery**
- **hit driven readout controlled by FSM**

The MightyPix Family

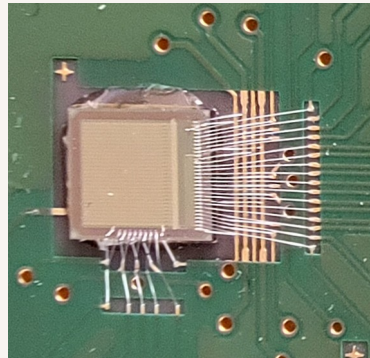
MightyPix1



TSI 180nm
Area: 5 mm x 20 mm
Pixel size:
50 μm x 165 μm

submitted 06/2022

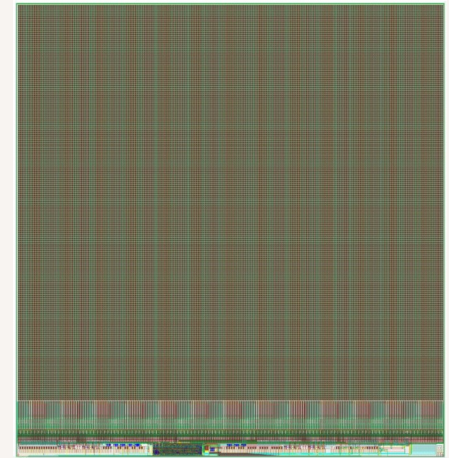
LF-MightyPix



LFoundry LF15
Area: 3.5 mm x 4 mm
Pixel size:
100 μm x 100 μm

submitted 05/2024

MightyPix2

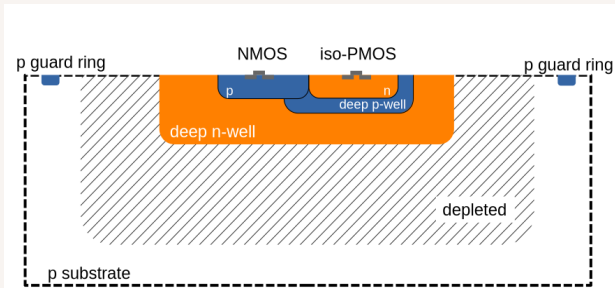


AMS ah18
Area: 21mm x 19mm
Pixel size:
84 μm x 84 μm

submitted 10/2025

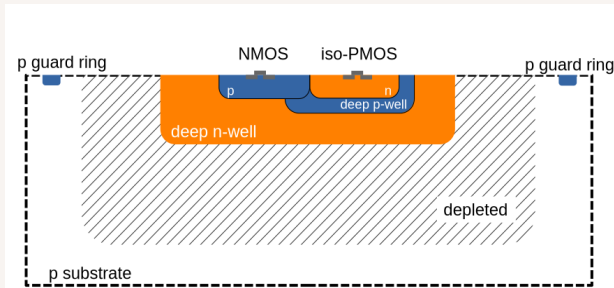
The MightyPix Family

MightyPix1



TSI 180nm
Amplifier-type: CMOS
Comparator: CMOS

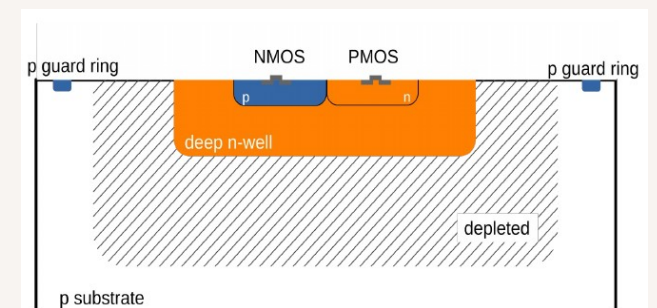
LF-MightyPix



Similar to MightyPix1, but
different chip guard ring design.

LFoundry LF15
Amplifier-type: NMOS
Comparator: CMOS

MightyPix2



AMS ah18
Amplifier: CMOS
Comparator: NMOS

MightyPix: Specific features for LHCb

TFC (fast commands@320Mbit/s)

ECS (configuration@10Mbit/s)

1280 / 640 / 320 Mb data link

Multiplexer 4:2, 4:1

Serial powering

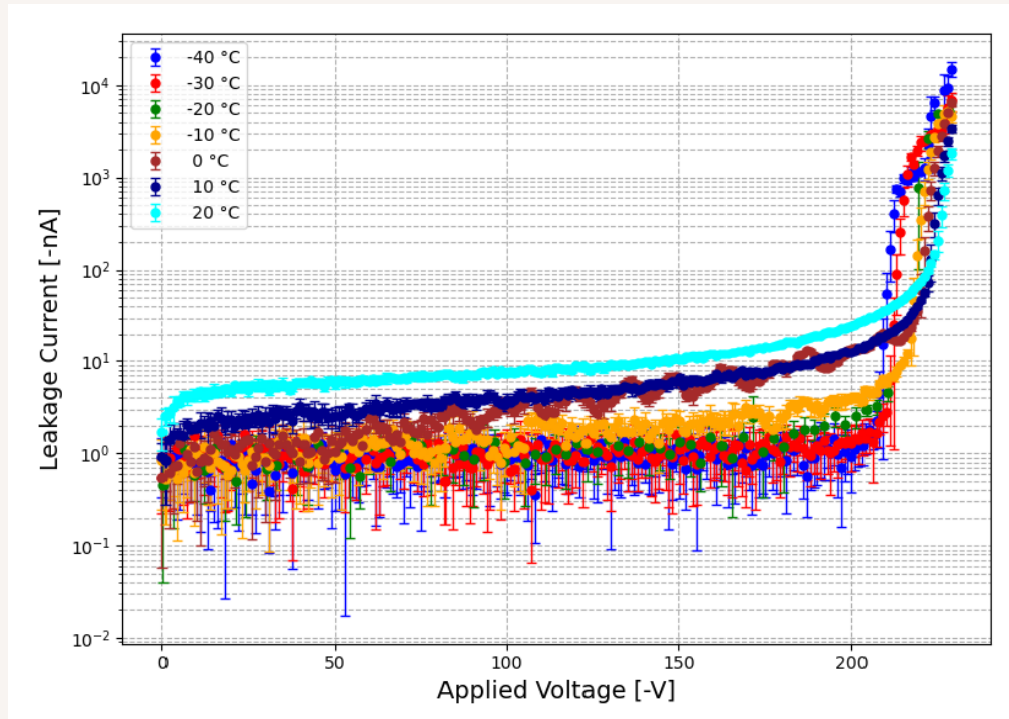
- shunt LDO's on chip

- DC balancing for all communication links (data, TFC, & ECS)

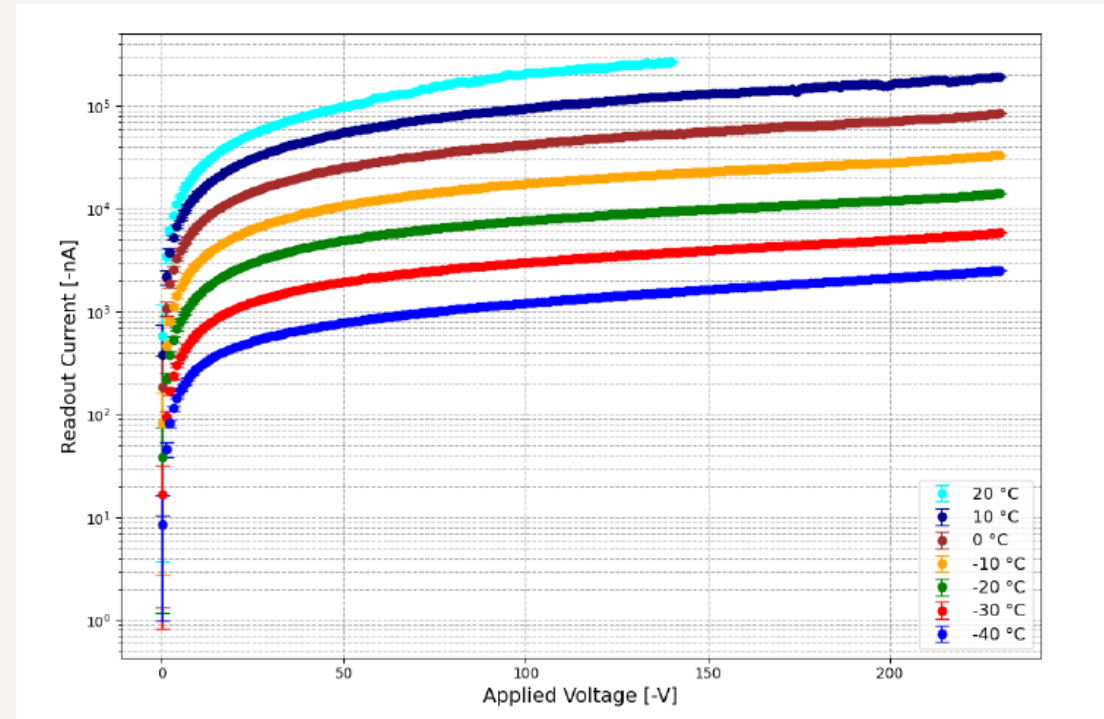
Hadronic environment → SEE

- triple redundant configuration & power on, glitch filter, hamming-2 encoded state variables to protect FSM implemented on MightyPix2

MightyPix1: IV curves

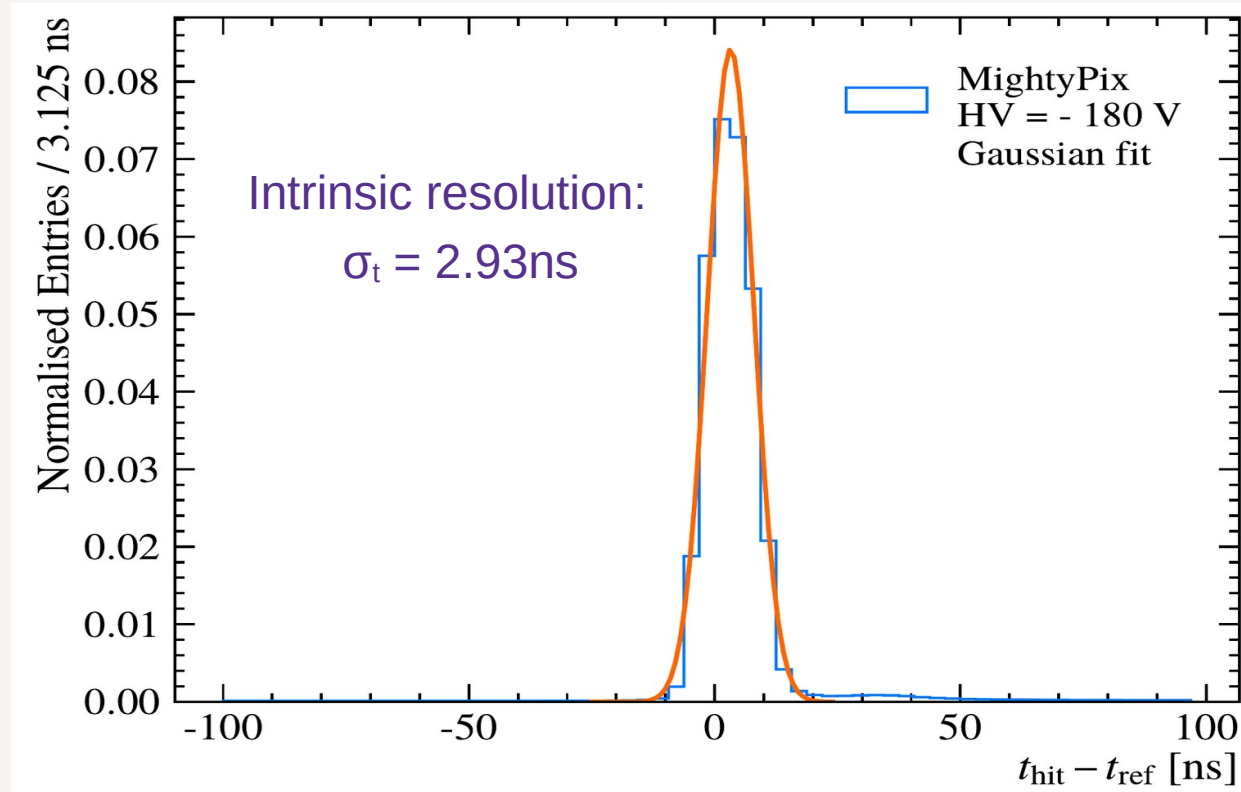


before irradiation



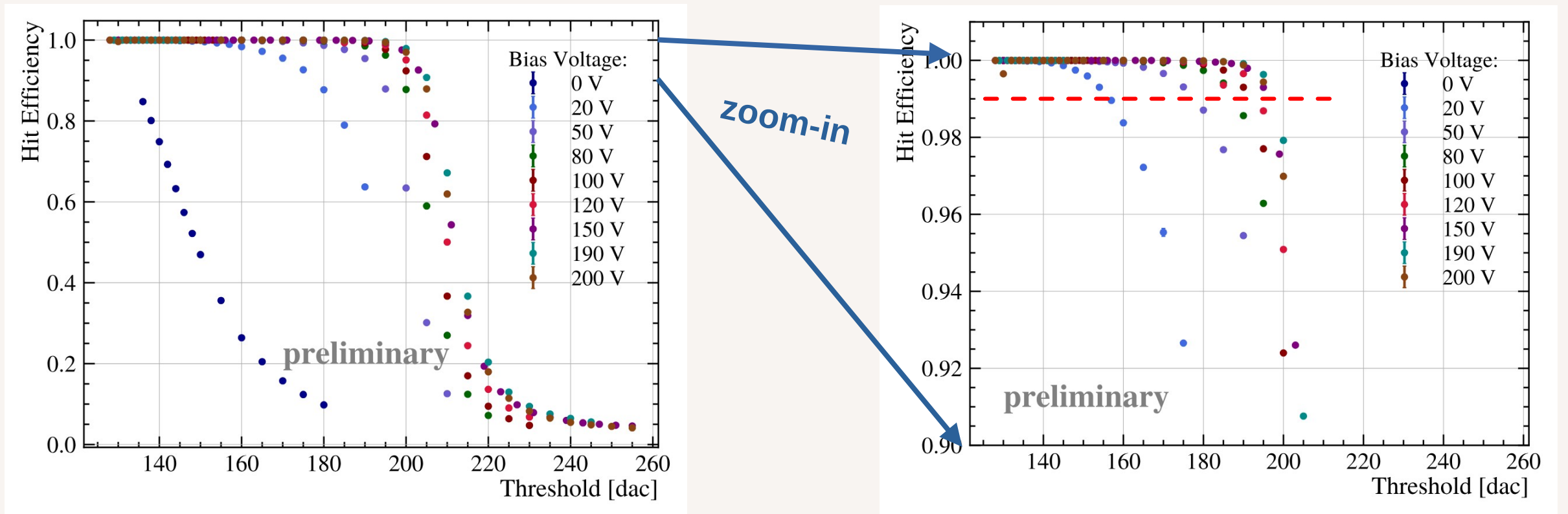
after $1 \times 10^{15} n_{eq}/cm^2$

MightyPix1: Time resolution

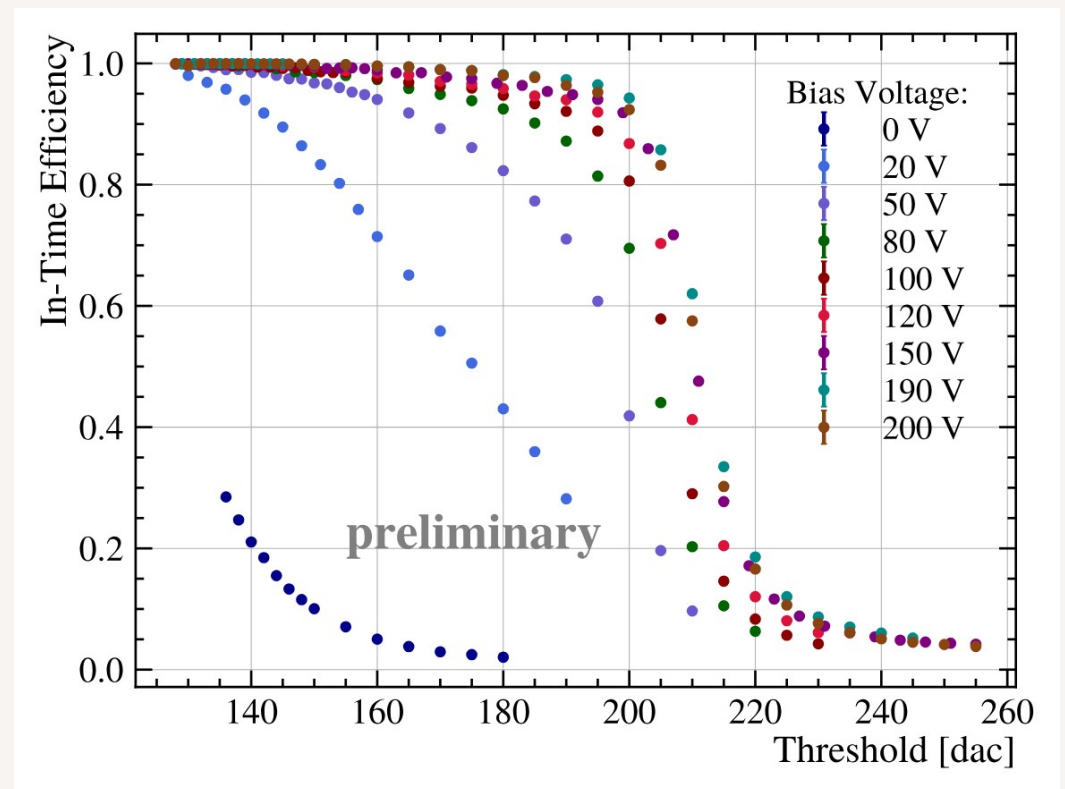
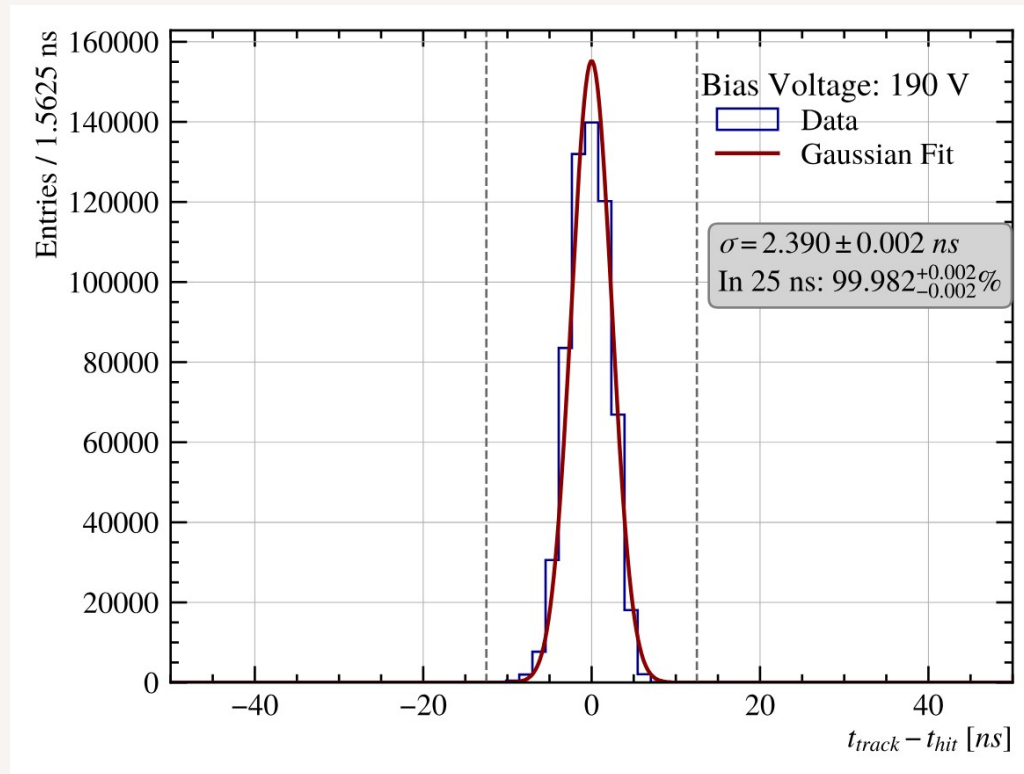


Only operational after FIB repair, but with very good performance demonstrated in lab with ^{90}Sr .

LF-MightyPix: Efficiency



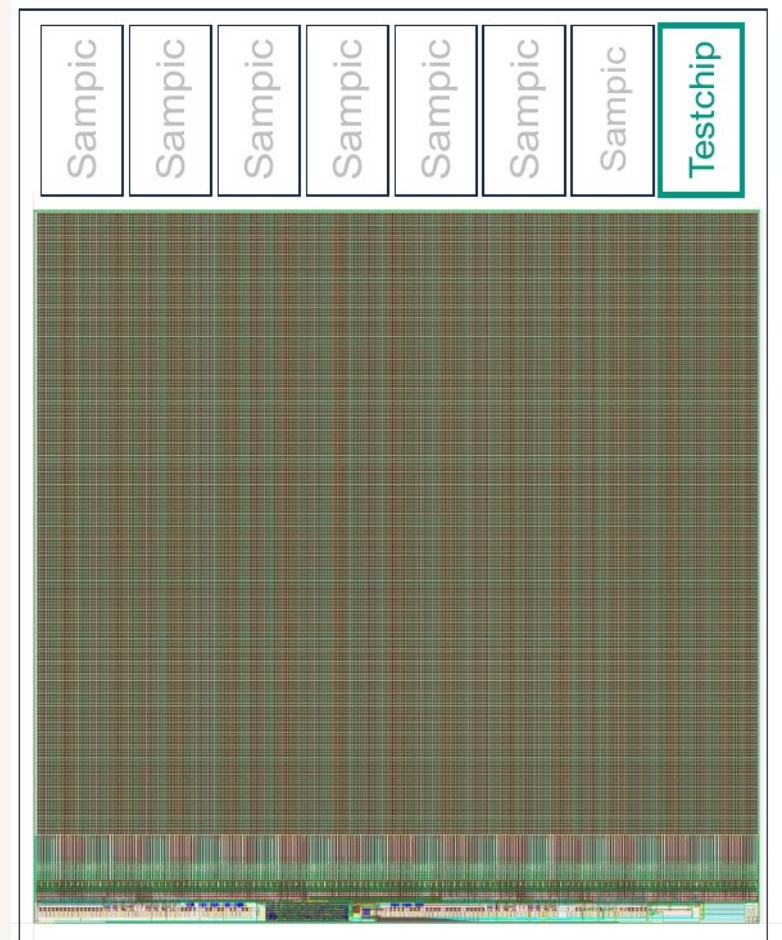
LF-MightyPix: In-time efficiency



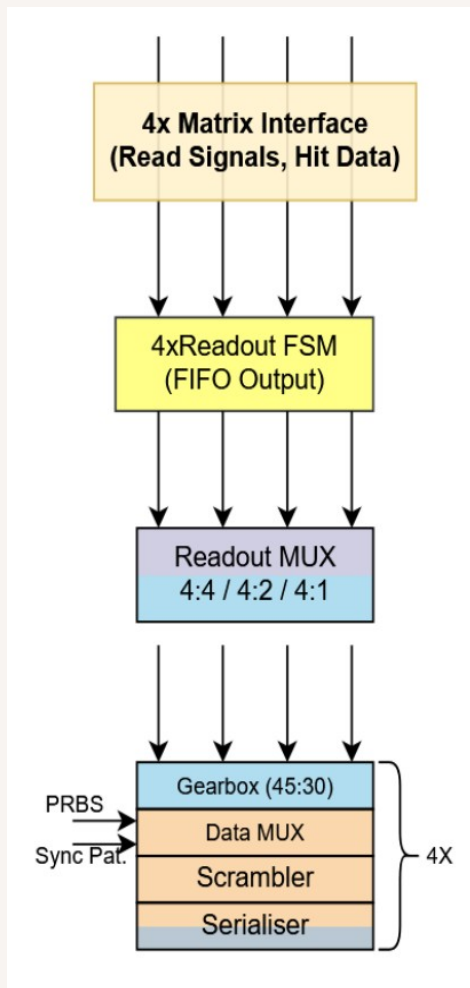
$$\text{In_Time Efficiency} = \text{In-Time Fraction} * \text{Efficiency}$$

MightyPix2: Overview

- o AMS ah18 engineering run
- o Features:
 - 244 x 194 pixel (full size: 244 x 240)
 - pixel size 84 μm x 84 μm
 - 21 x 19 mm²
 - **fully compatibility to LHCb**
(TFC, ECS, readout architecture, serial powering...)
- o Dedicated chip with test-structures
 - > allow systematic studies on TID damage, SEU & serial powering



MightyPix2: readout & rate simulation



Rate simulation:

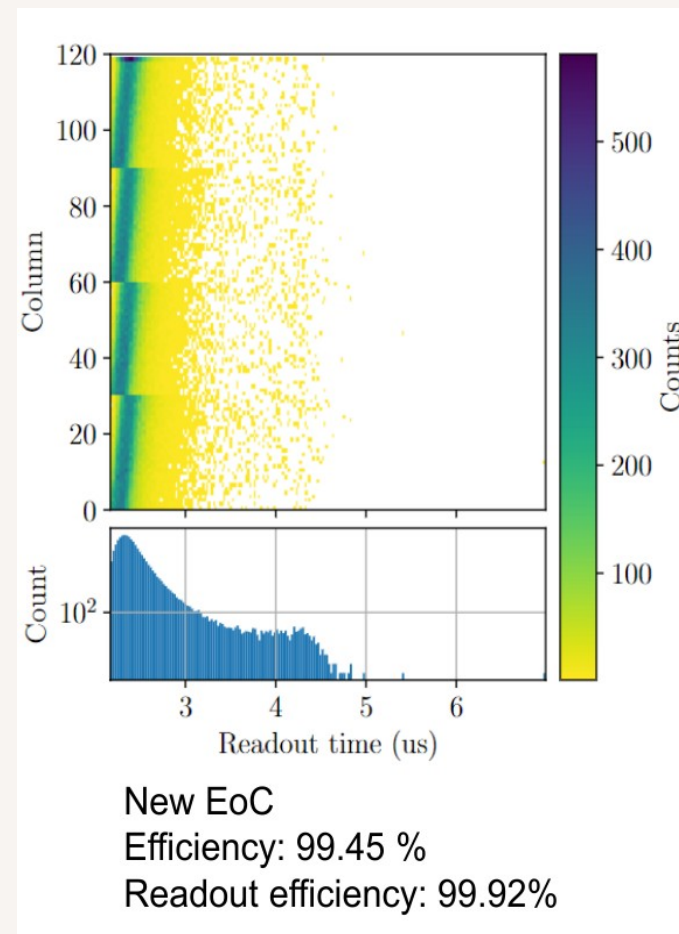
Dedicated software tool* to verify hit rate capability.

Set-up:

- full pixel matrix
- actual MP2 readout design
- p-p run conditions
- Hit rate of 35MHz^2

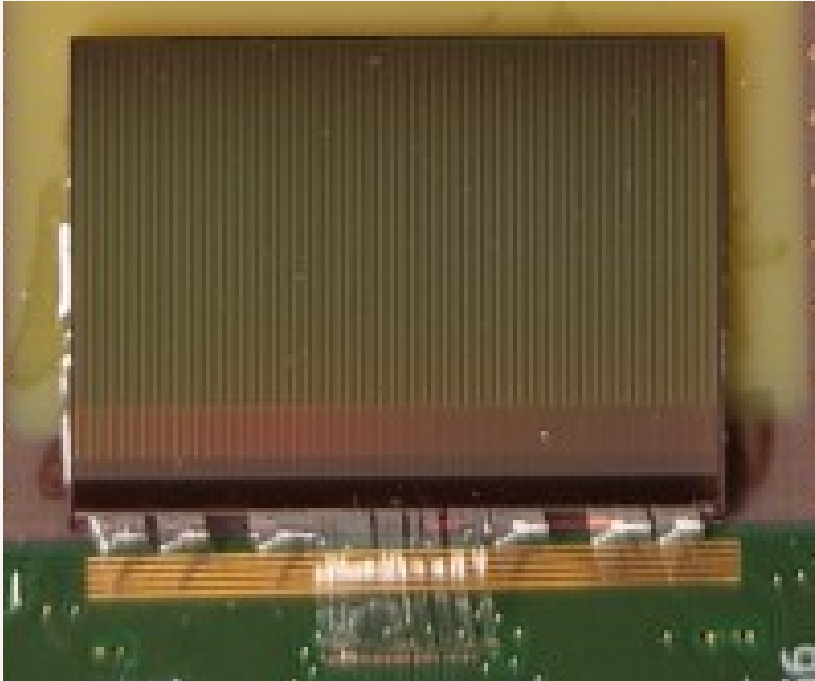
Result:

- Very high readout efficiency from improved EOC
- Speed limited by links



* [MightyPix at the LHCb Mighty Tracker — verification of an HV-CMOS pixel chip's digital readout](#)
S. Scherl (Liverpool U. and KIT, Karlsruhe, IPE) et.al. DOI: [10.1088/1748-0221/19/04/C04045](https://doi.org/10.1088/1748-0221/19/04/C04045)

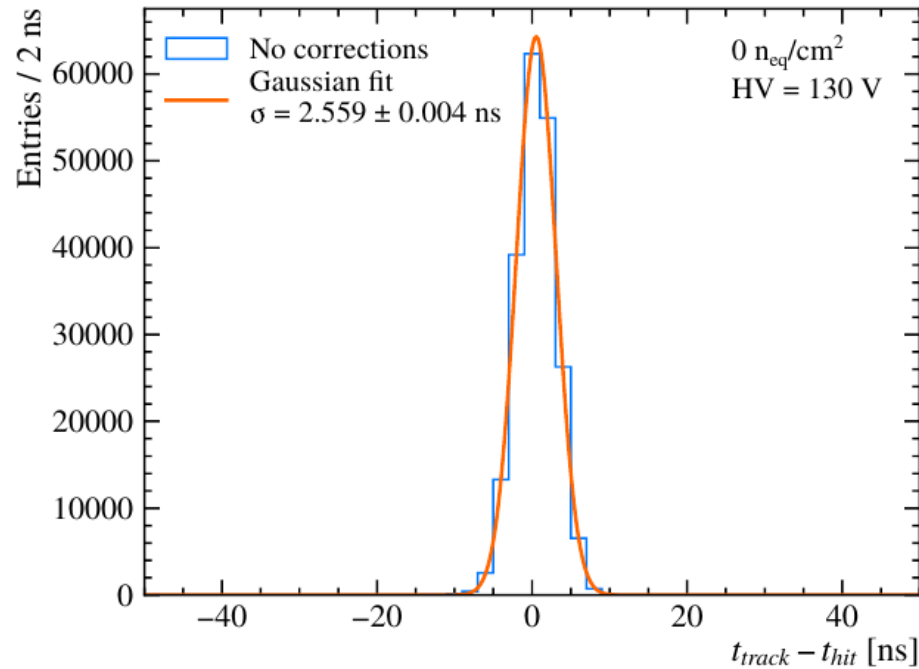
Radiation hardness of HV-MAPS: TelePix2 as a primer for MightyPix



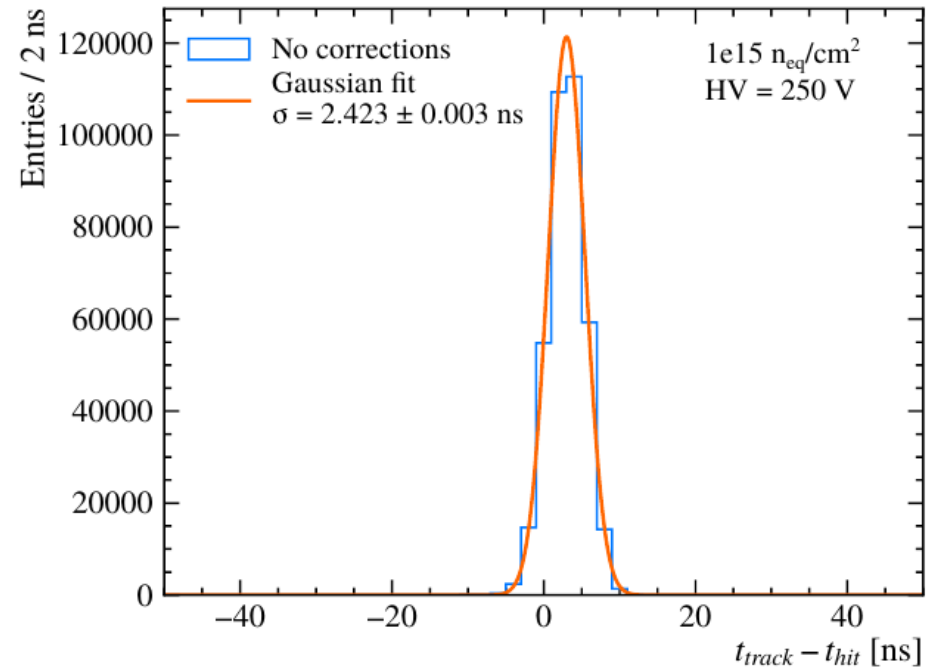
* [arXiv:2503.08177](https://arxiv.org/abs/2503.08177)

- developed as time reference for DESY test beam telescope *
- foundry, substrate and design of pixel array same as MightyPix1, except pixel size:
 - 165 μm x 25 μm for TelePix2
 - 165 μm x 50 μm for MightyPix1
- several irradiation campaigns:
 - NIEL: up to $1 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$
 - TID: high dose/high rate up to 40 MRad
 - low dose/low rate up to 1-2 MRad

Time resolution after neutron irradiation



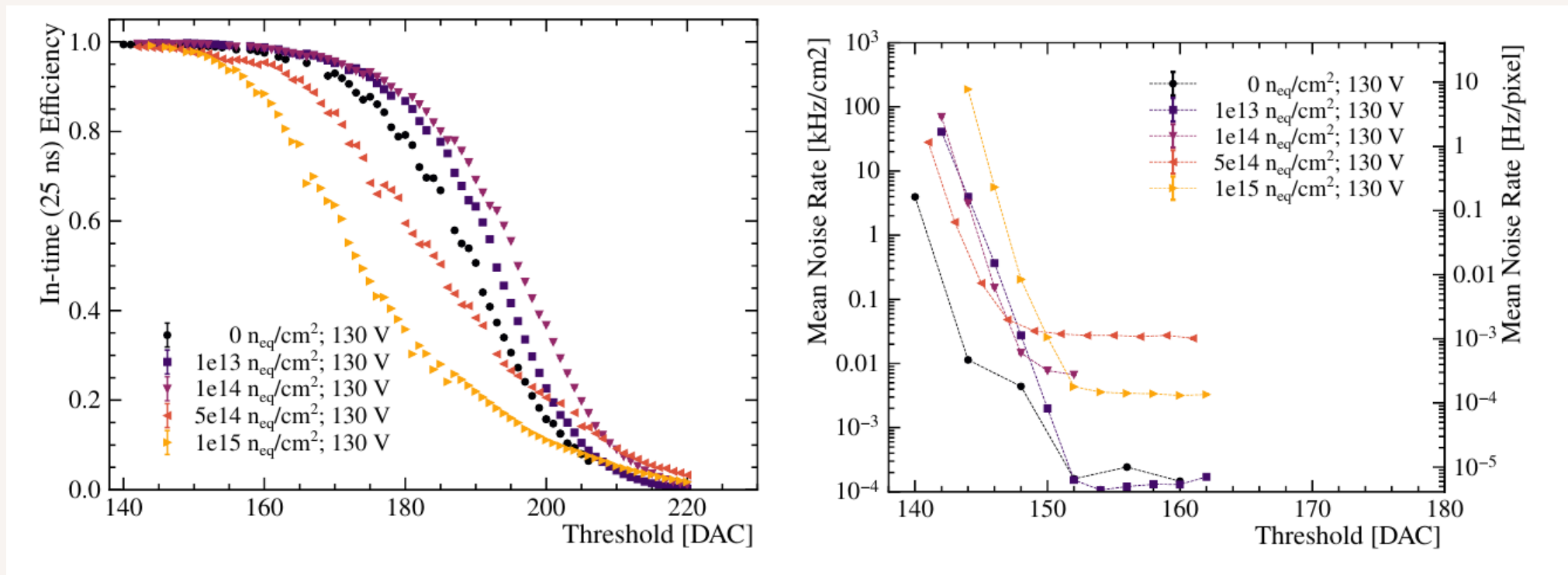
before irradiation



after $1 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$

In-time efficiency & noise after neutron irradiation

Constant voltage for all fluences

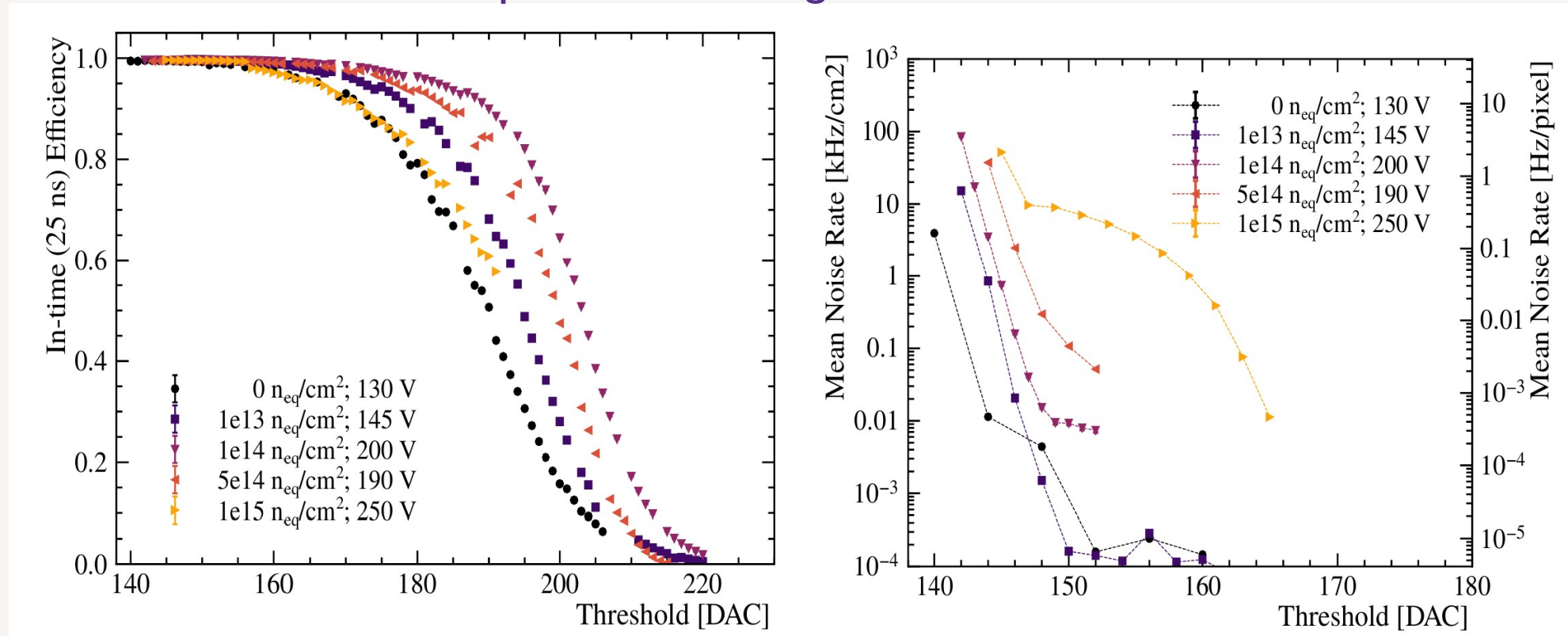


In-time efficiency

Noise rate

In-time efficiency & noise after neutron irradiation

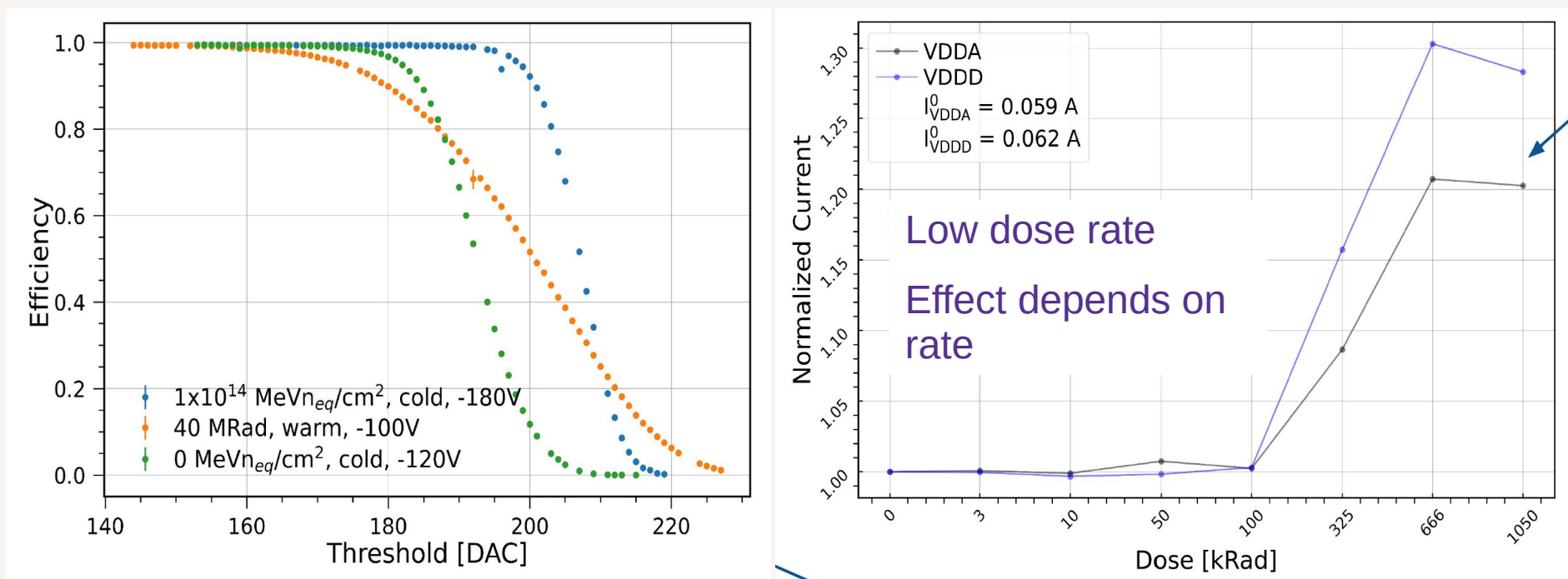
Max. operation voltage for all fluences



In-time efficiency

Noise rate

Efficiency & power consumption after TID irradiation

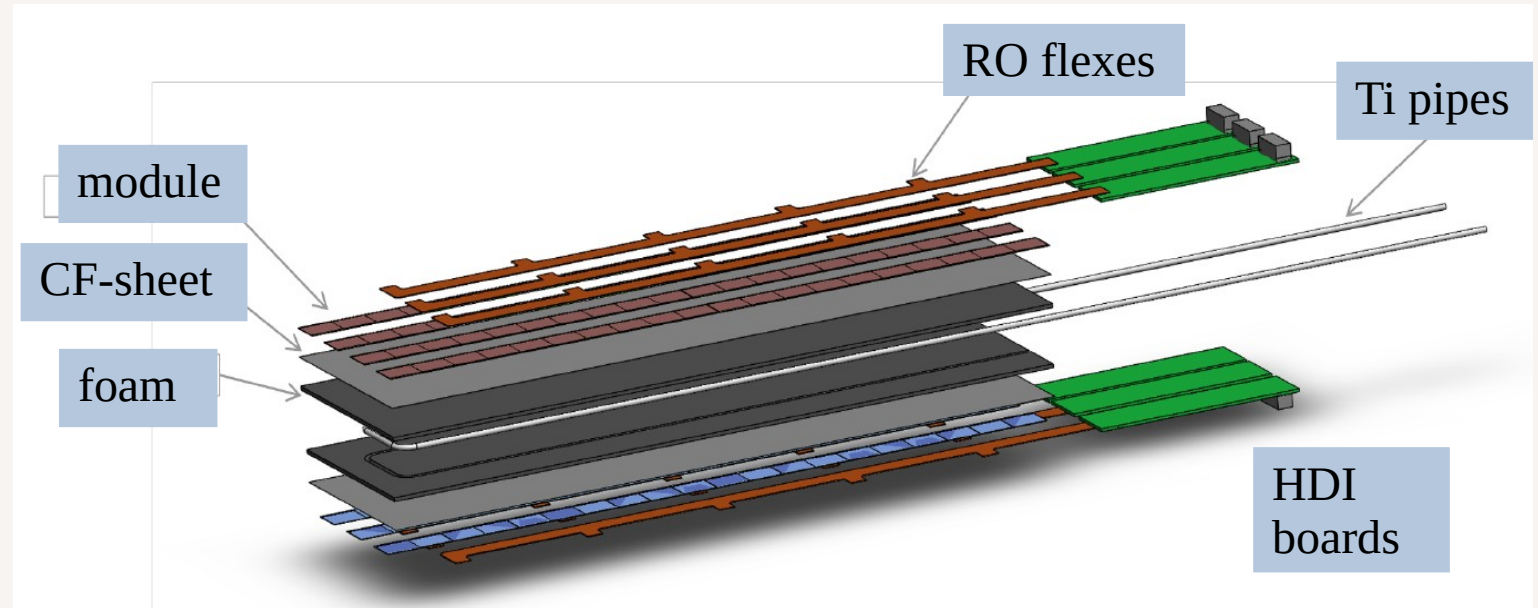


Acceptable performance after irradiation with protons and X-rays, but spurious increase of low voltage currents. Dose rate dependent effect, under investigation.

FULL STAVE

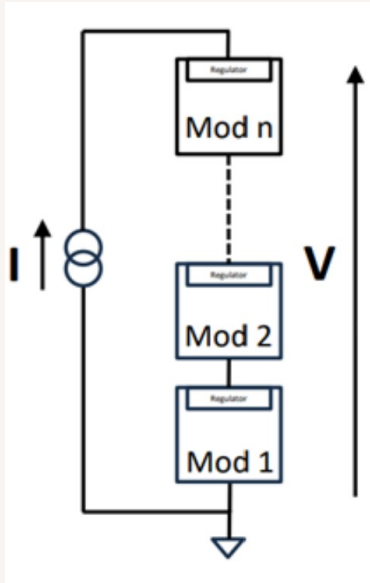
Assembly:

- 6 columns, each housing 6 modules a 5 sensors i.e. 180 sensors per stave
- Core:
CF sandwich panel with heat conducting foam and Titanium cooling pipe
- Readout flex:
Length depends on position of HDI

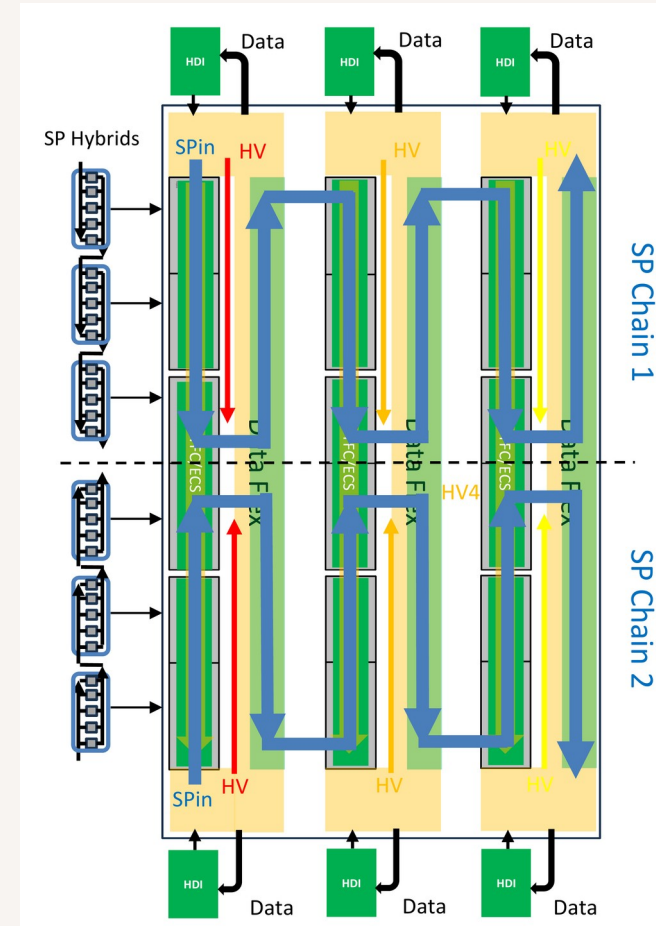


POWERING SCHEME

Serial powering:



- To minimize material budget serial powering of MightyPix sensors is foreseen
- A module contains 5 sensors which are powered in parallel
- Two serial power chains per full stave containing 30 modules / 180 sensors



SUMMARY & CONCLUSION

- LHCb aims for an Upgrade for LHC Run 5 to cope an increase in luminosity by a factor of 5
- Inner region of current downstream tracker (scintillating fibre tracker) has to be replaced by a pixel detector
- The HV-MAPS based MightyPix sensor is currently developed for the Mighty-Tracker with MightyPix2 being the first sensor fully compatible for the application in LHCb
- Radiation hardness of the technology has been demonstrated
- We aim for a TDR in autumn 2026

Backup

SPECIFICATIONS

MightyTracker-Pix

EDMS no. 3207186

Parameter	MP Specification
Pixel size (bending plane)	$\leq 100 \mu\text{m}$
Pixel size (non bending plane)	$\leq 200 \mu\text{m}$
Substrate thickness	$< 200 \mu\text{m}$
Pixel orientation	x
Max. Particle Rate	17 MHz/cm ²
Max. Hit Rate	34MHz cm ⁻²
Max. length of data word	32
Overall efficiency	>96%
In-time efficiency	>99% within 25 ns
Noise rate (End of life)	$\leq 400\text{kHz/cm}^2$
Transmission rate	4 links of 1.28Gbit/s each
NIEL	$3 \times 10^{14} n_{\text{eq}}/\text{cm}^2$
TID	40 MRad
Power Consumption	$\leq 150 \text{ mW/cm}^2$

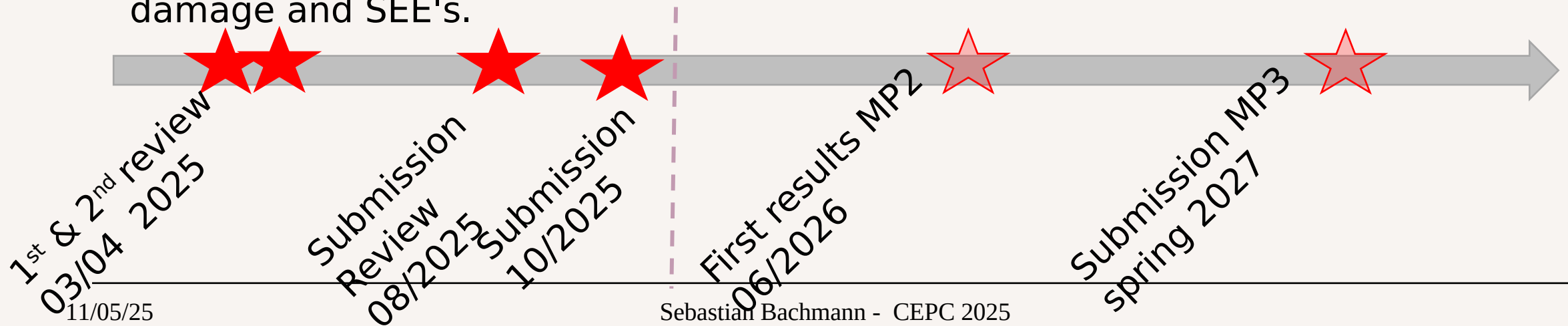
Upstream Pixel

Yiming's slide from LHCC ASIC review

Parameters	UP Specification	Remarks
<i>Sensor size</i>	$\sim 2 \times 2 \text{ cm}^2$	Common with MT
<i>Pixel size, square</i>	$\leq 85 \times 85 \mu\text{m}^2$	
<i>Pixel size, rectangular</i>	$\leq 50 \times 200 \mu\text{m}^2$	
<i>Substrate thickness</i>	$< 200 \mu\text{m}$	
<i>Pixel orientation</i>	x	bending plane
<i>Max. Particle Rate</i>	50 MHz/cm ²	from Geant 4 + Pythia, @ 4 cm radius previously 74 MHz/cm ² @ $\mathcal{L} = 1.5 \times 10^{34} \text{ cm}^{-2}\text{s}^{-1}$
<i>Max. Hit Rate</i>	100 Mhit/cm ²	at 4 cm radius, 100 % margin
<i>Max. length of data word</i>	32	
<i>Overall efficiency</i>	> 96 %	Including dead area
<i>In-time efficiency</i>	> 99 % with in 25 ns	
<i>Noise rate (End of life)</i>	$\leq 400 \text{ kHz/cm}^2$	@ max. 1% masked channels
<i>Transmission rate</i>	$N \times 1.28 \text{ Gbit/s}$	$N \leq 7$ for matching with 1 LpGBT
<i>NIEL</i>	$4 \times 10^{15} N_{\text{eq}}/\text{cm}^2$	from Fluka, safety margin 4
<i>TID</i>	250 Mrad	from Fluka, safety margin 4
<i>Power Consumption</i>	$\leq 200 \text{ mW/cm}^2$	no margin, budget $\sim 10 \mu\text{A/pixel}$ ($85 \times 85 \mu\text{m}^2$ pixel)

MP2 status and timeline:

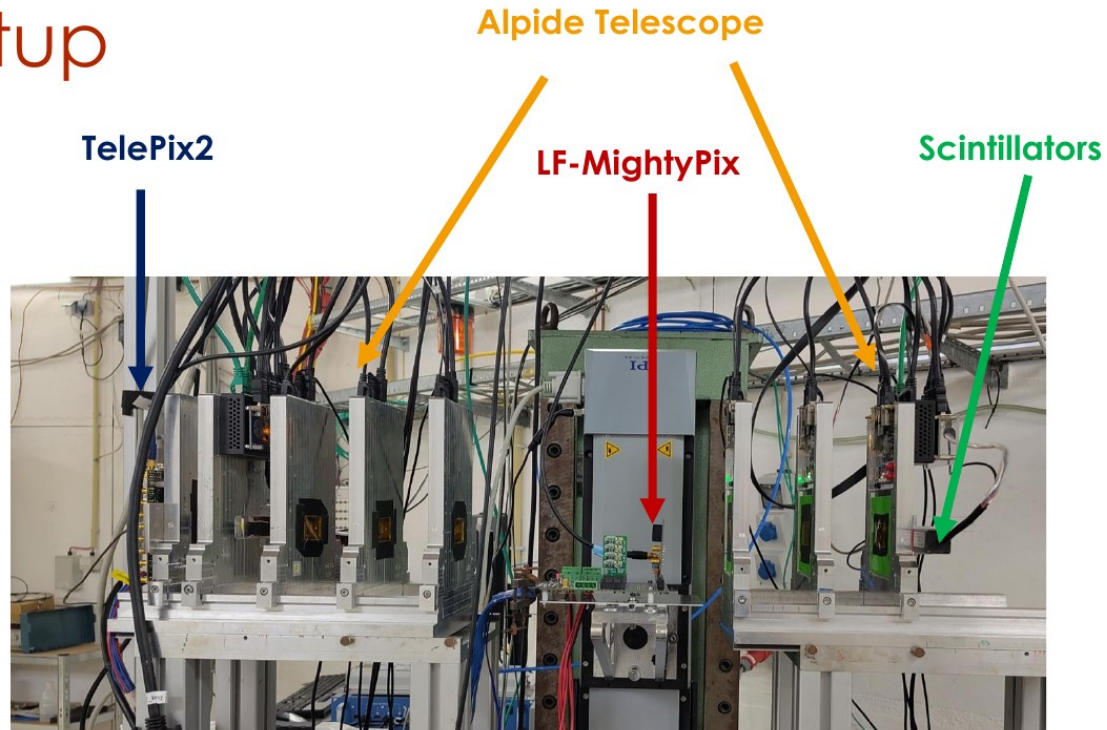
- o MightyPix2 is designed for full compliance to the LHCb specifications.
- o MightyPix2 has undergone a thorough review process with fruitful discussions. Recommendations have been implemented since then, especially on protection against single event effects (SEE).
- o Critical issues to be demonstrated with MightyPix2 are tolerance wrt TID damage and SEE's.



DESY Testbeam (13/10 – 2/11/2025)

Test Beam Setup

- DESY Testbeam Area 22
 - 4 GeV electrons
 - Alpide Telescope
 - TelePix2 Time Reference
- Running parasitically to Mu3e/P2
- LF-MightyPix readout using Gecco
- Data Analysis in Corryvreckan



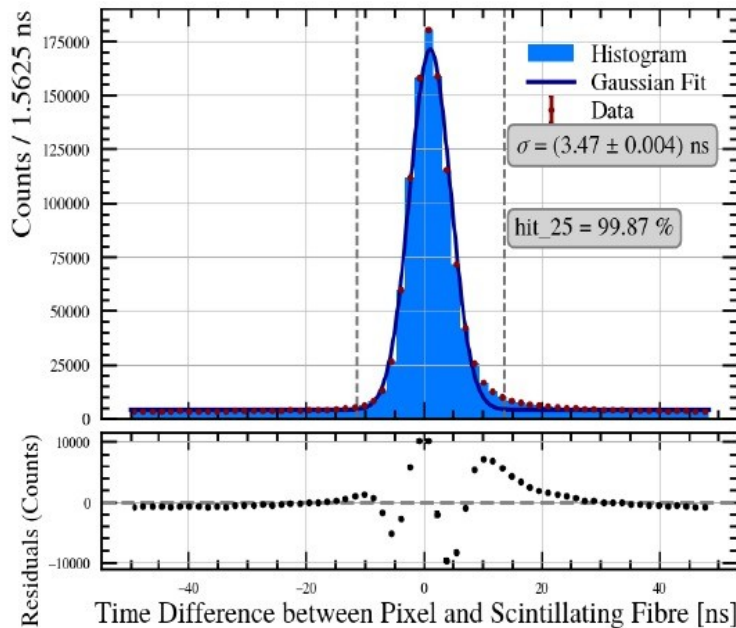
22.10.2025

Celina Welschoff

3

LF-MightyPix: Lab measurements (Sr-90)

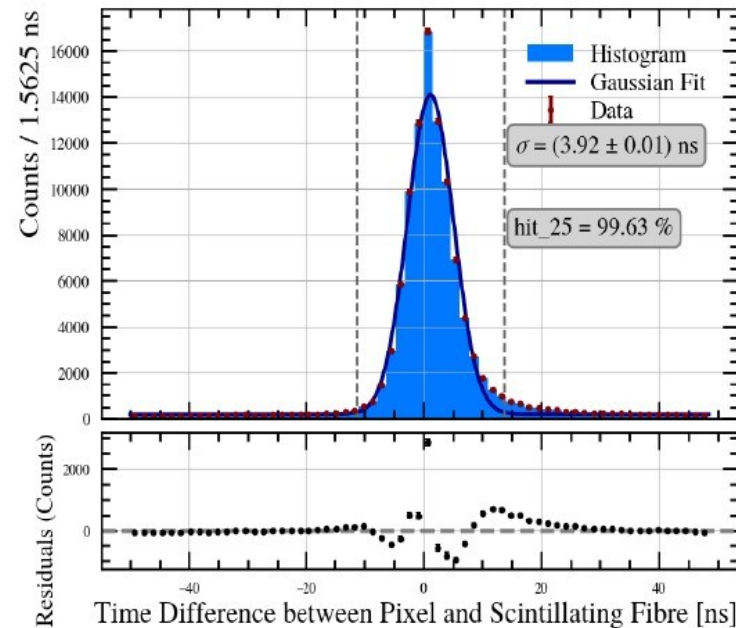
Digital Optimum DACs



Power Consumption :

20.65 $\mu\text{W}/\text{Pixel}$ or 201 mW/cm^2

Analogue Optimum DACs



Power Consumption :

19.25 $\mu\text{W}/\text{Pixel}$ or 193 mW/cm^2

Excellent time resolution at reasonable low power consumption.

Definition of hit_25:

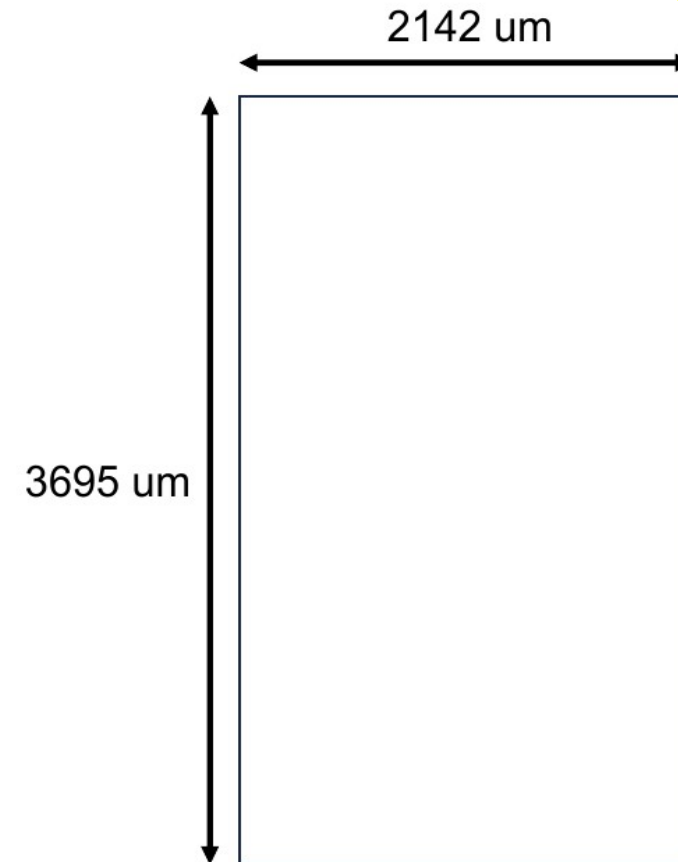
In-Time-Fraction =

$$\frac{\text{Number of hits in 25 ns}}{\text{Total number of hits}}$$

Conservative estimate
Of power consumption

Dedicated Chip for Teststructures

- TID measurements
 - NMOS/PMOS
 - Rectangular long/short W/L
 - ELT
 - DRAM: Evaluate data retention time
 - SRAM: Evaluate static noise margin
- SEU/SET cross section measurements
 - DRAM
 - SRAM
 - TMR Configuration Registers
- Serial Powering
 - 2 SLDOs for serial/parallel configuration



Nicolas Striebig

SEU/SET Improvements

■ Glitch Filter

- SET glitch filter for async reset input
- Reset synchronizers TMR protected

■ Hamming 2-encoded state variables

- 1 additional FF to detected single bit errors
- Reduced risk of incorrectly jumping into invalid state
- Allows monitoring -> Error output connected to Counter

■ TMR

■ TFC

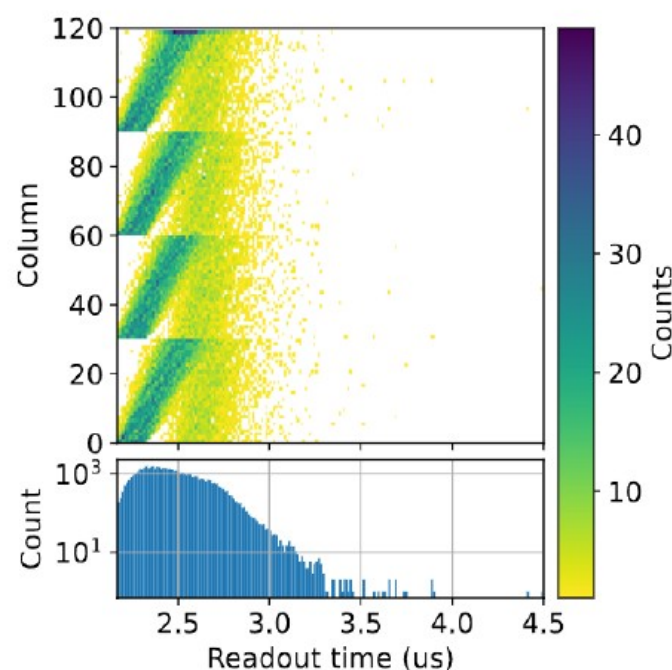
- Slow clock domain part TMR protected
- Deserializer part unprotected, but all single bit errors can be detected due to 6b8b encoding -> SEE can cause bitflip -> Receiver unlock
- Clock tree is not triplicated, SET could cause bitflip -> Receiver unlock

■ Registers

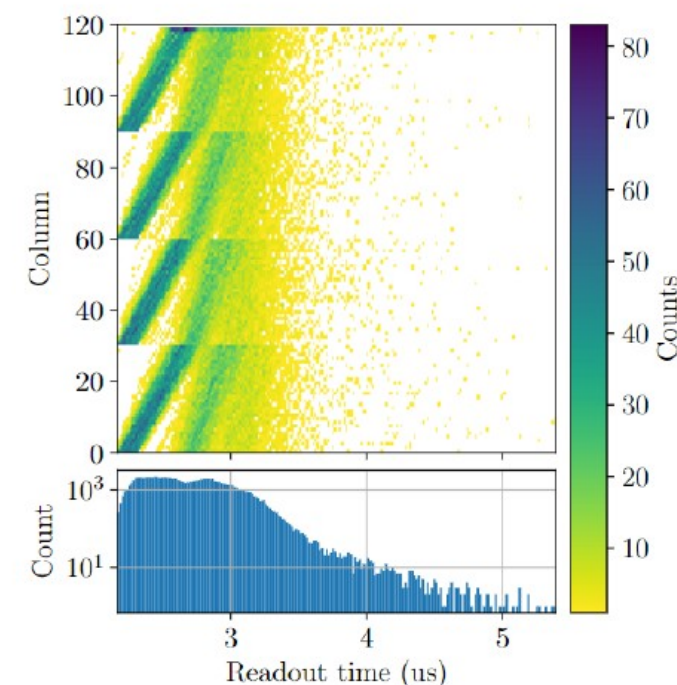
- Registerfile partially and chip configuration completely TMR protected

Rate Simulation – Heavy Ion

- Heavy Ion run conditions
- 50 ns bunches
- 0.25 % interaction propability
- Much higher peak hitrate



Avg. 20 hits/interaction/cm²
Efficiency: 99.98 %
Readout efficiency: 99.98%



Avg. 40 hits/interaction/cm²
Efficiency: 99.97 %
Readout efficiency: 99.98%